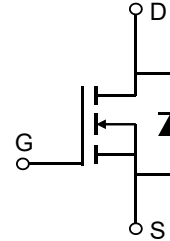


### Description

#### Features

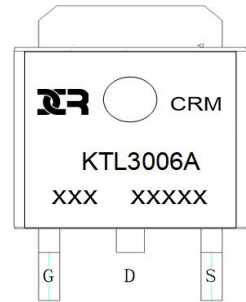
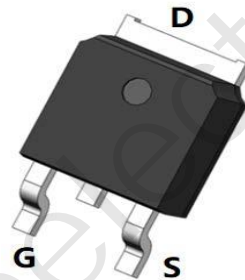
- 30V, 90A
- $R_{DS(ON)}$  Typ = 4mΩ @  $V_{GS} = 10V$
- $R_{DS(ON)}$  Typ = 7.9mΩ @  $V_{GS} = 4.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Excellent CdV/dt effect decline
- 100% UIS TESTED!
- 100%  $\Delta V_{ds}$  TESTED!



Schematic Diagram

#### Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

#### Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMKTL3006A	CRMKTL3006A	TO-252-3L	TAPING	13"	2500	25000

#### Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	30	V
$V_{GS}$	Gate-to-Source Voltage	±20	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$	90
		$T_C = 100^\circ\text{C}$	54
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	360	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	95	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}$	72.2
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.73	°C/W
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	°C

### Electrical Characteristics ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V	-	-	1.0	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
On Characteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1	1.4	2	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 30A	-	4	5.2	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 20A	-	7.9	9.5	mΩ
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 15V, f = 1MHz	-	1916	-	pF
C <sub>oss</sub>	Output Capacitance		-	217	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	183	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 0 to 10V V <sub>DS</sub> = 15V, I <sub>D</sub> = 30A	-	37	-	nC
Q <sub>gs</sub>	Gate Source Charge		-	7.4	-	nC
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	8.6	-	nC
Switching Characteristics						
t <sub>d(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 15V I <sub>D</sub> = 30A, R <sub>GEN</sub> = 3Ω	-	8.4	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	20	-	ns
t <sub>d(off)</sub>	Turn-Off DelayTime		-	32	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	9	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current	V <sub>GS</sub> = 0V, I <sub>S</sub> = 20A	-	-	90	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	360	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage		-	-	1.2	V
trr	Body Diode Reverse Recovery Time		-	10.2	-	ns
Qrr	Body Diode Reverse Recovery Charge		I <sub>F</sub> = 20A, di/dt = 100A/us	-	2.75	-

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
  2.  $E_{AS}$  condition: Starting  $T_J = 25^\circ\text{C}$ ,  $V_{DD} = 15\text{V}$ ,  $V_G = 10\text{V}$ ,  $R_G = 25\Omega$ ,  $L = 0.5\text{mH}$ ,  $I_{AS} = 19.5\text{A}$
  3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .

## Test Circuit

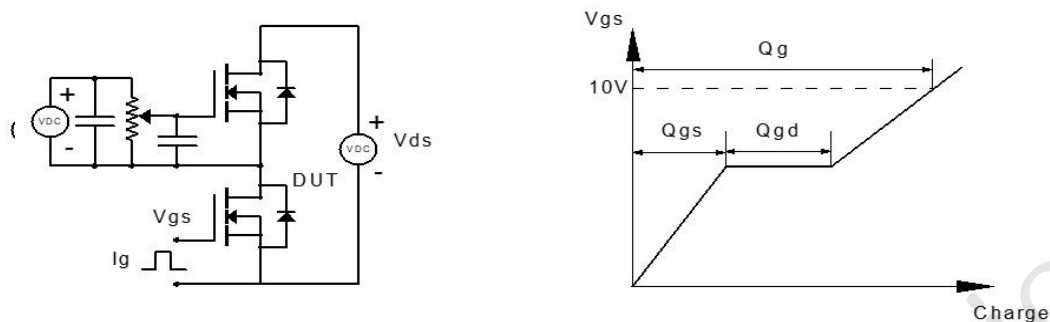


Figure 1: Gate Charge Test Circuit & Waveform

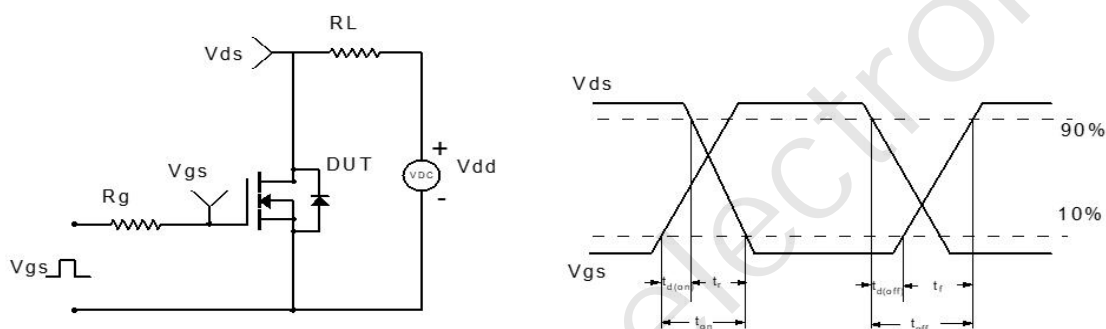


Figure 2: Resistive Switching Test Circuit & Waveform

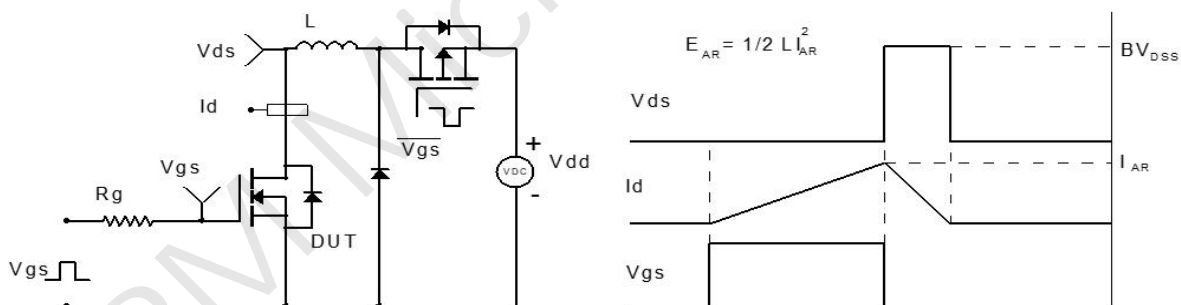


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

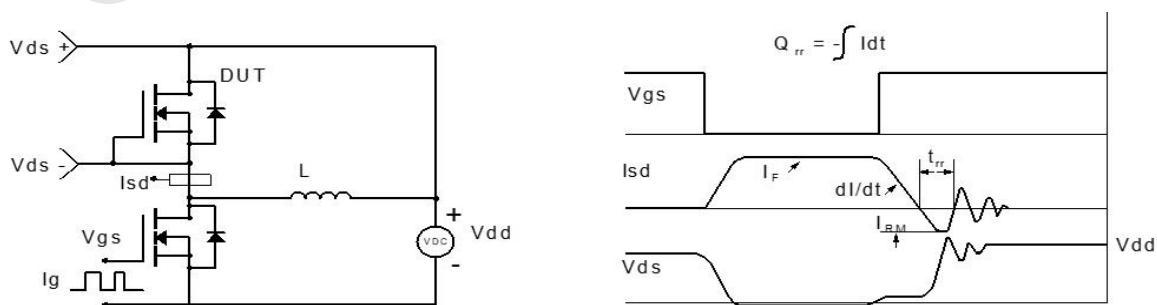
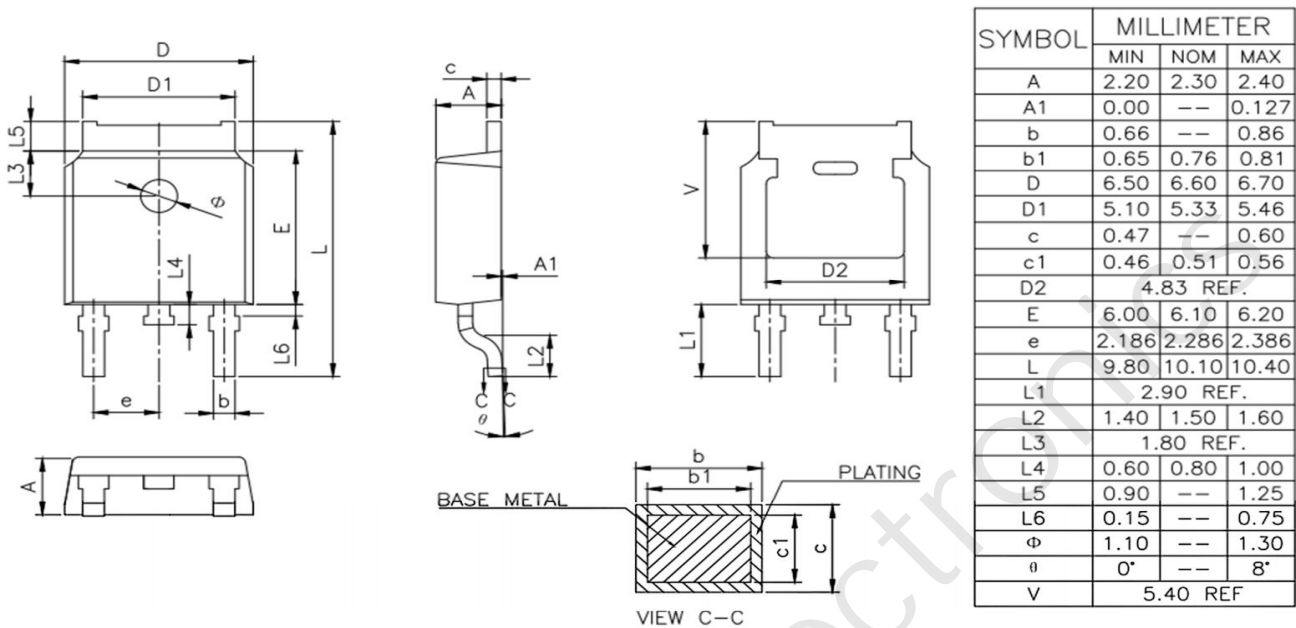


Figure 4: Diode Recovery Test Circuit & Waveform

### Package Mechanical Data(TO-252-3L)




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